

FIG. 1 (PRIOR ART)

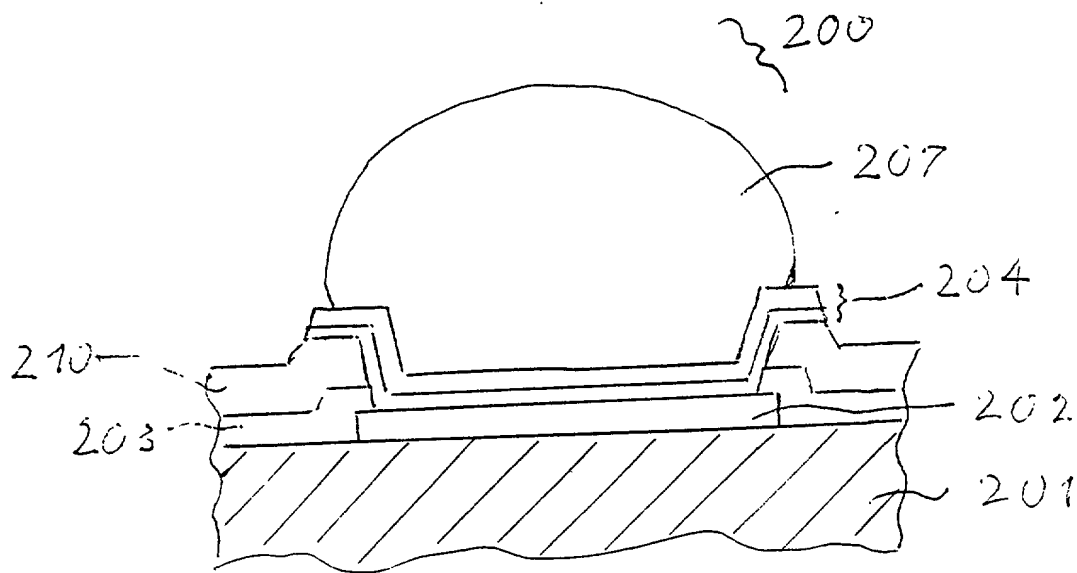


FIG. 2 (PRIOR ART)

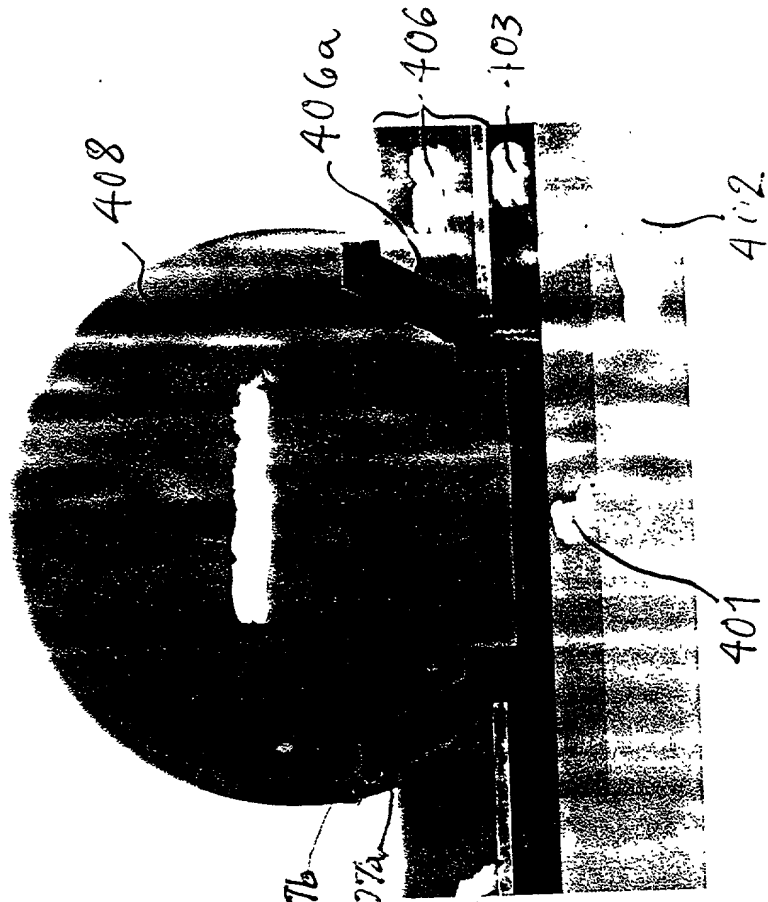


FIG. 3
(PRIOR ART)

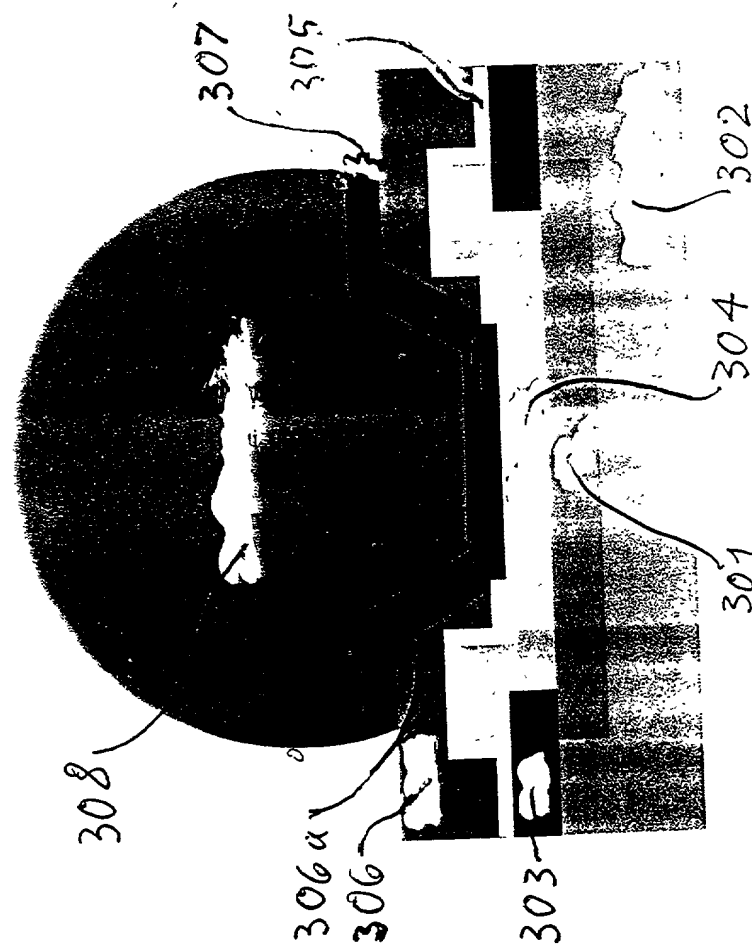


FIG. 4
(PRIOR ART)

FIG. 500

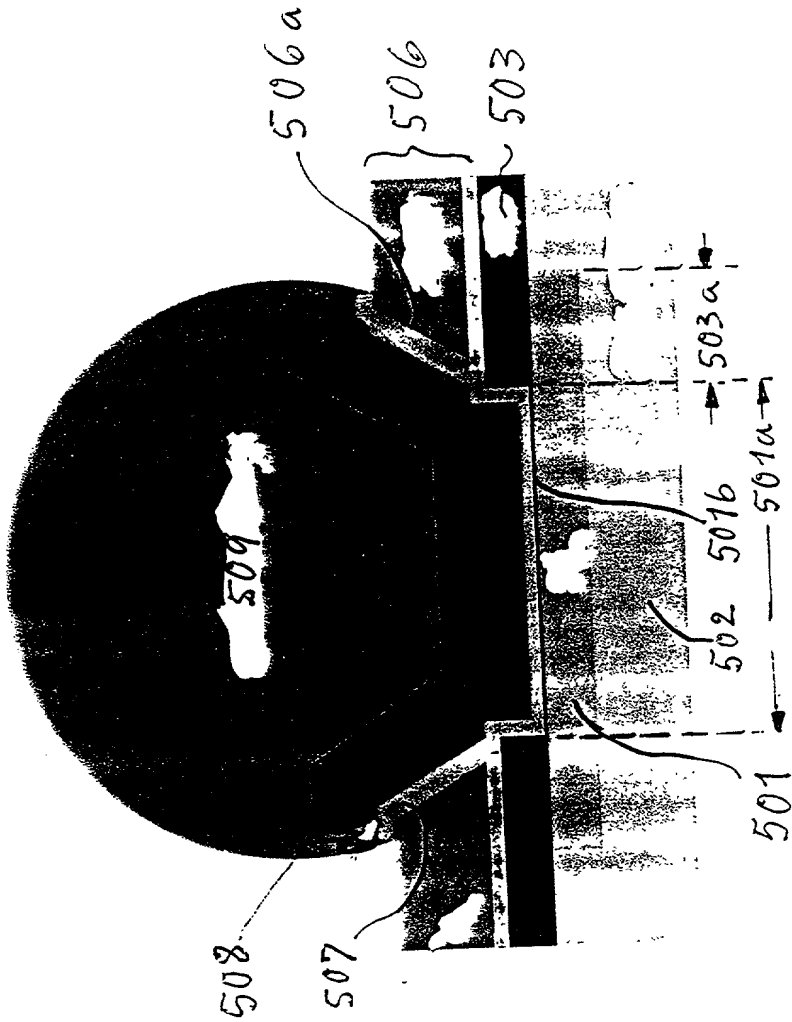


FIG. 5

FIG. 6: Process Flow
for Direct Bumping on Copper Pads

